Lanner

PARTNER BRIEF

5G Open RAN Solution

Radisys

Open RAN refers to a Radio Access Network (RAN) which is open, intelligent, and deployed on a virtualized platform with high flexibility. Open RAN is about disaggregating hardware from software: open hardware and software using standard processors with open interfaces.

Lanner collaborate with Radisys to create a high-performance, containerized-based 5G Open RAN solution with flexible deployment options for various industries. The cost-effective, fully disaggregated Open RAN solution includes Lanner's Open RAN appliance and Radisys' Open RAN Software, delivering secure, real-time communication for enabling low-latency services for mission-critical applications.

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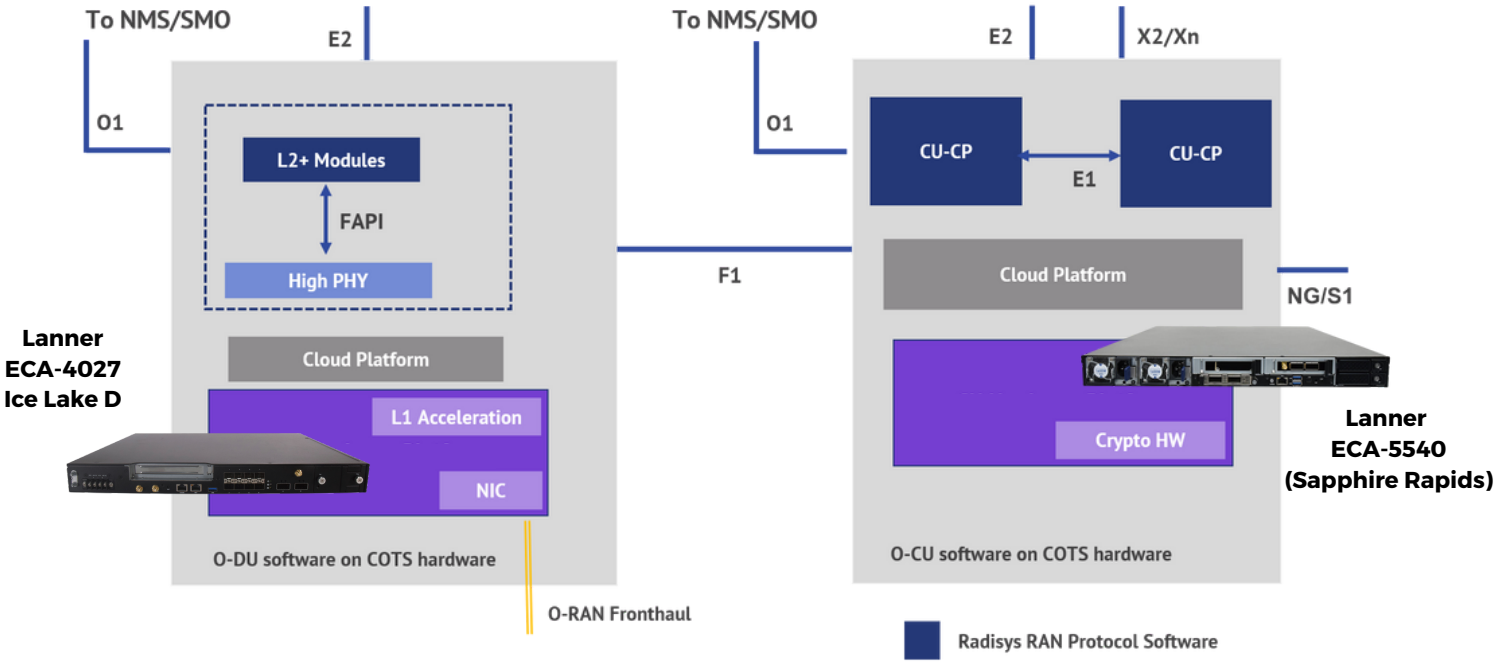
Open RAN Software Solution



Radisys RAN Software

Radisys Connect 5G software suite, based on a modular approach to Open RAN, expands the possibilities for building networks that deliver the high capacity, massive connectivity, and ultra-low latency required for 5G services.

5G NR Software Architecture
Highly interoperable to provide ease of integration with your existing and new network ecosystem.

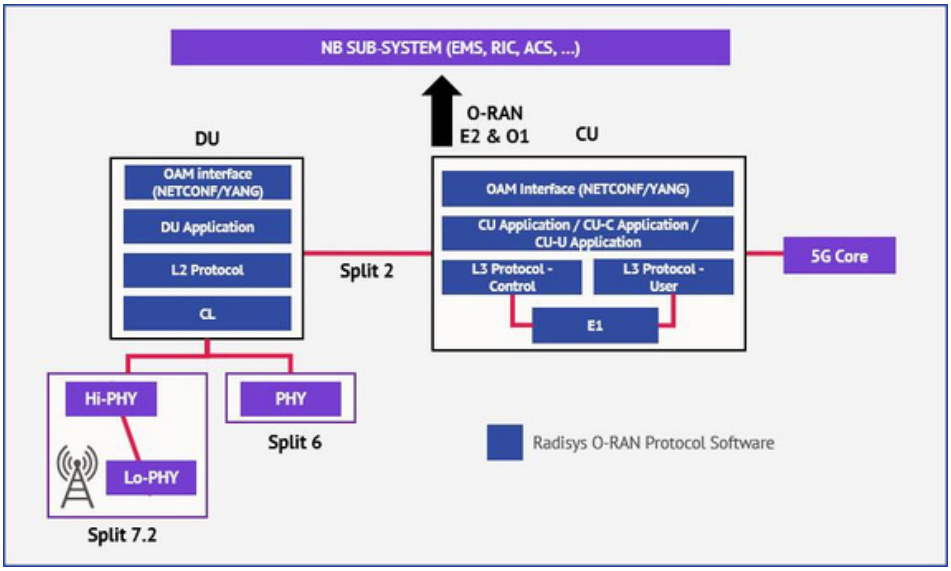
MULTIPLE OPERATIONAL MODES
Supports both standalone (SA) and non-standalone (NSA) modes

FREQUENCY RANGE
FR-1 (sub-6 GHz) and FR-2 (mmWave)

DISAGGREGATION AND RAN SPLITS
Support split 7.2 (vRAN model)

CLOUD-NATIVE DESIGN
All RAN software is available in bare-metal as well as containerized form factor (over native Kubernetes as Docker pods)

O-RAN COMPLIANCE
Open northbound APIs over E2 and O1 O-RAN interfaces



DU/CU Server ECA-4027

- Intel® Xeon D-2100 12/16 Cores Processor
- Wide Operating Temperature -40~65°C
- 2x DDR4 2667 MHz REG, ECC RDIMM, Max. 128GB
- Front Access I/O: 1x GbE RJ45 IPMI, 8x 10G SFP+, 2x 40G QSFP+, 1x RJ45 Console, 1x USB 3.0 and Front Fan Replacement
- 2x 2.5" Internal HDD/SSD Bays, 2x M.2 NVMe 2280 M key
- 1x PCI-E*16 FH/HL slot for vRAN accelerator
- G.8272 T-GM Compliant IEEE 1588v2 SynE, onboard GPS

DU/CU Server ECA-5540

- Intel® Sapphire Rapids EE Processor with Intel vRAN Boost
- Short Depth Chassis and Front I/O Design
- 16x DDR5 4400MHz RDIMM, Max. 1024GB
- 1x OCP 3.0 NIC Module
- 0 ~ 55°C Operating Temperature
- 2x M.2 NVMe 2280, 2x 2.5" SATA/ U.2
- 1x FHFL PCIex 16 slot, 2xLP or 1xFHHL slot (PCIex8)
- Secure BMC / TPM 2.0

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